ANT + *Bluetooth*® Single-Chip, Dual-Mode Module

FEATURES

- **Fully Qualified Bluetooth v2.1 + Enhanced Data Rate (EDR)**
- **ANT+ capable**
- **Bluetooth and ANT Smart Priority Mechanism Allows Flexible Coexistence and Simultaneous Operation**
- **+10 dBm Typical Tx Power with Transmit Power Control**
- **- 93 dBm Typical Receiver Sensitivity**
- **Support for Bluetooth Power Saving Modes (Sniff, Hold)**
- **Low Power Scan Method for Page and Inquiry Scans at 1/3rd Normal Power**
- **Fast Algorithm for Both ACL and eSCO**
- **Host Controlled Interface (HCI) Supports Three and Four Wire UART Transport with Rates of up to 4Mbps**
- **Hardware and Software Pre-integration with TI's MSP430 Ultra Low-power Microcontroller**
- **Dimensions: 9 mm x 9.5 mm x 1.8 mm (CC2567-PAN1327, Integrated Antenna); 6.5 mm x 9.5 mm x 1.8 mm (CC2567-PAN1317, Without Antenna)"**
- **Bluetooth, FCC, CE, IC Certified**
- **Operating Temperature Range: -20C° to 70°C**

APPLICATIONS

- **ANT+ and Bluetooth Aggregators**
- **Sports and fitness devices**
- **Health and wellness devices**
- **Ability to add ultra low-power ANT+ technology to existing Bluetooth solutions**
- **Connect current ANT+ applications to mobile phones and computers via Bluetooth**

DESCRIPTION

The following product brief applies to Panasonic's Bluetooth module, series number: PAN1327 and PAN1317. The Bluetooth chip used is the CC2567 from Texas Instruments.

The CC2567-PAN1327/17 is the first dual-mode, ANT and Bluetooth solution in the market. This solution is a highly-integrated class 2 HCI module with increased output power capabilities offered by Panasonic using TI's CC2567 ANT+ and Bluetooth 2.1 + Enhanced Data Rate (EDR) dual-mode transceiver. Based on TI's 7th generation Bluetooth technology, the solution provides best-in-class Bluetooth RF performance of +10 dBm typical Tx power and -93 dBm typical receiver sensitivity. The CC2567-PAN1327/17 module allows customers to connect to mobile phones and computers over Bluetooth from ANT+ enabled devices, and allows customers with Bluetooth solutions to add ultra low-power ANT+ connectivity. This solution is provided as a module to help customers reduce development time, lower manufacturing costs, save board space, ease certification, and minimize RF expertise required. For evaluation and development, a platform is available that integrates the CC2567-PAN1327/17 module, Bluetooth stack, Serial Port Profile, ANT+ solution and sample source applications running on a TI host controller – MSP430.

The full specification and purchasing of the CC2567-PAN1327/17 can be found on Panasonic's website (www.panasonic.com/ti). The development kit for this solution is available for order today through the ANT + Bluetooth Health and Fitness Aggregator Kit tool folder (www.ti.com/cc2567_pan1327_antbtkit). More information on TI's wireless platform solutions can be found on TI's Wireless Connectivity Wiki (www.ti.com/connectivitywiki).

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